

ABSTRACT

A method of packaging a device and an apparatus formed by the method. According to one embodiment, the apparatus includes a base connected to the device, and a cover. The cover includes an injection molded plastic body and at least one electrically conductive lead. The body
5 of the cover is connected to the base such that the device is enclosed by the cover, and the electrically conductive lead includes an exposed portion that is electrically connected to the device.